

PLATING

Surface mount sockets for IC packages!

These unique sockets have slotted tails to provide added adhesion to the solder paste and greater solder joint strength. The high temperature LCP body is ideal for vapor phase or infrared soldering.

Precision stamped three-finger CONTACT micro contacts provide exceptional reliability and performance.

Specifications: ICF HI-TEMP

Insulator Material: Black Liquid Crystal Polymer Contact Material: BeCu

Current Rating:

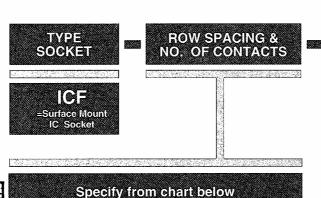
Operating Temp Range: -65°C to +125°C Max Processing Temp: 230°C for 60 seconds Plating: Au or Sn over 50μ" (1,27μm) Ni Contact Resistance:

Tontact Hesistan 10 mΩ Max Insertion Depth: .100" (2,54mm) to .150" (3,81mm) Insertion Force: 5oz (1,39N) average Withdrawal Force:

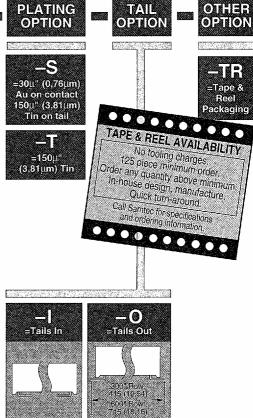
4oz (1,11N) average SMT Lead Coplanarity: .006" (0,15mm) max

Note:

Some sizes, styles and options are non-standard, non-returnable



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		"–XXX"		Row Space	No. of Contacts		
1.			٦		08		
		-314 -316 -318 -320		.300 (7,62)	14 16 18 20		
							+1.17
		-322			22		
		-324			24		- 4
		-328	\perp		28 24 28 32		
		-624	Ц				
		-628	_				
		-632	4	.600 (15,24)			
		-640 -648			40 48		
	* •	— (2,54) . ⁻	100	X No. of Spa	cës —— (O)	<u>†</u> ⊕	Other Suppl
(7,62) .300 or (15,24)		ÙŬ	U		ŬŬ	Ĭ	Row Spacing + (1,91)
(15,24) .600 <u>y</u>	} ●		0		1	0	
		— (2,54) .1ı	00	(2,54).→ 100 TYP X No. of Posit	ions		
(4.57) .180							
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TAIL

